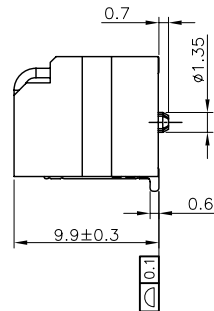
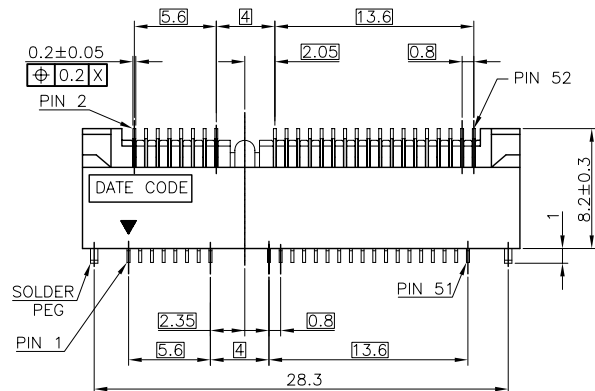
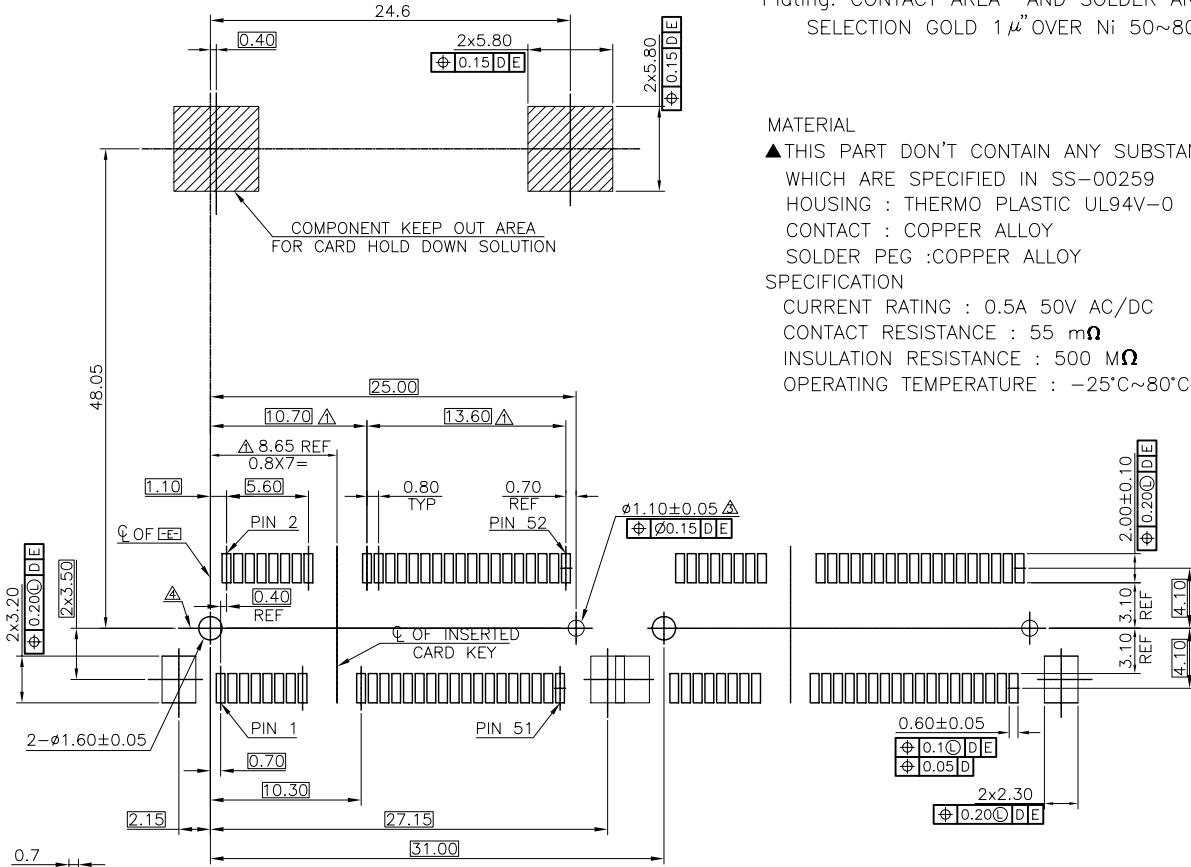
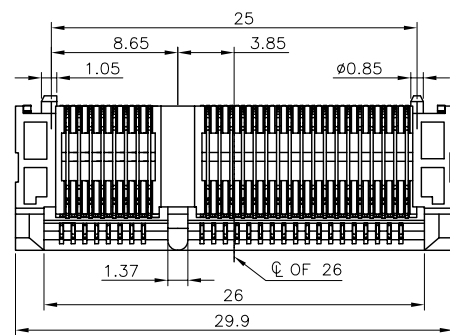


REV.	DESCRIPTION	DATE	DWN	APVD
1	PRELIMINARY	27APR09	JC	BC

Plating: CONTACT AREA AND SOLDER AREA :
SELECTION GOLD 1μ" OVER Ni 50~80

MATERIAL
 ▲ THIS PART DON'T CONTAIN ANY SUBSTANCES
 WHICH ARE SPECIFIED IN SS-00259
 HOUSING : THERMO PLASTIC UL94V-0
 CONTACT : COPPER ALLOY
 SOLDER PEG : COPPER ALLOY
 SPECIFICATION
 CURRENT RATING : 0.5A 50V AC/DC
 CONTACT RESISTANCE : 55 mΩ
 INSULATION RESISTANCE : 500 MΩ
 OPERATING TEMPERATURE : -25°C~80°C



RECOMMENDED P.C.BOARD PATTERN LAYOUT
(SIDE BY SIDE)

GOLD FLASH	J27-0008-01
MIN. GOLD THICKNESS	PART NUMBER

TOLERANCES UNLESS OTHERWISE SPECIFIED:		DWN 27APR2009		HAOGUO XING YE SHARE CO.,LTD.	
0 PLC	± -	CHK	JOHN_CHANG		
1 PLC	± 0.3	CHK	MARKS_CHEN	NAME	
2 PLC	± 0.2	APVD	27APR2009		
3 PLC	± -	PRODUCT SPEC		0.80MM PITCH MINI PCI EXPRESS H=9.9mm CONNECTOR CUSTOMER DRAWING	
4 PLC	± -	APPLICATION SPEC			
ANGLES	± 3°	FINISH		SIZE	
MATERIAL		SEE NOTE			
FINISH		SEE NOTE		RESTRICTED TO	
PROJECTION		WEIGHT			
DIMENSIONS:		- GRAMS		CUSTOMER DRAWING	
		MM			
				SHEET 1 OF 1	
				REV 1	